U.S. Pat. Appl. No.: 10/757,735

## Amendments to the Claims:

The following listing of claims will replace all prior versions and/or listings of claims in the application.

## Listing of Claims:

- (Currently Amended) An electromagnetic (EM) shielding assembly for shielding an 1. electronic component mounted on a circuit board, the assembly comprising:
  - an electrically conductive shielding portion mountable adjacent the electronic [[-]] component at least partially to surround the electronic component; and
  - at least one resiliently biased electrically conductive connection member in [[-]] electrical communication with the shielding portion and operable electrically to connect the shielding portion to a predetermined voltage by bearing down upon an electrically conductive contact of the circuit board forming a solder-less detachable electrical connection between the resiliently biased electrically conductive connection member and the electrically conductive contact.
- (Original) The EM shielding assembly of Claim 1, wherein a surface of the shielding 2. portion defines a cavity for receiving one of the at least one connection members.
- (Original) The EM shielding assembly of Claim 2, comprising a plurality of said 3. connection members and wherein the surface of the shielding portion defines a plurality of cavities each for receiving a respective one of the connection members.
- (Original) The EM shielding assembly of Claim 3, the shielding portion having a first 4. plurality of cooling members extending away therefrom, each cooling member accommodating a respective one of said cavities.

- 5. (Original) The EM shielding assembly of Claim 4, the shielding portion having a second plurality of cooling members extending away therefrom.
- 6. (Original) The EM shielding assembly of Claim 5, wherein the first plurality of cooling members are arranged around a periphery of the electronic component.
- 7. (Original) The EM shielding assembly of Claim 2, comprising a retainer for preventing removal of the at least one connecting member from the cavity.
- 8. (Original) The EM shielding assembly of Claim 1, wherein the shielding portion is mounted on the electronic component.
- 9. (Original) The EM shielding assembly of Claim 1, comprising a mounting strut for mounting the shielding portion on the circuit board.
- 10. (Original) The EM shielding assembly of Claim 1 comprising a plurality of said connection members arranged to extend along a peripheral edge of said electronic component to form a shielding cage around said component.
- 11. (Original) The EM shielding assembly of Claim 10 further comprising one or more support members, each support member being attached to at least two connection members to provide support therefor.
- 12. (Original) The EM shielding assembly of Claim 11, wherein the one or more support members are electrically conductive.

13. (Original) The EM shielding assembly of Claim 1, wherein at least one of the electrically conductive shielding portion and said at least one electrically conductive connection member are metal.

- 14. (Currently Amended) Apparatus comprising a circuit board having an electrically conductive contact for providing a connection to a predetermined voltage, an electronic component mounted on the circuit board, and an electromagnetic (EM) shielding assembly, the EM shielding assembly comprising:
  - [[-]] an electrically conductive shielding portion mounted adjacent the electronic component and at least partially surrounding the electronic component; and
  - [[-]] at least one resiliently biased electrically conductive connection member in electrical communication with the shielding portion and electrically connecting the shielding portion to the predetermined voltage by bearing down upon the electrically conductive contact forming a solder-less detachable electrical connection between the resiliently biased electrically conductive connection member and the electrically conductive contact.
- 15. (Cancelled).
- 16. (Original) The apparatus of Claim 14, further comprising an opening in the circuit board in which said connection member is received, an interior surface of the opening being coated with an electrically conductive layer forming said electrically conductive contact.
- 17. (Original) The apparatus of Claim 14, comprising a plurality of said connection members, each connection member bearing down upon the electrically conductive contact.

- 18. (Original) The apparatus of Claim 14, the circuit board having a plurality of said electrically conductive contacts, the EM shielding assembly comprising a plurality of said connection members, each connection member bearing down upon a respective one of the electrically conductive contacts.
- 19. (Currently Amended) Electromagnetic (EM) shielding means for shielding an electronic component mounted on a circuit board, the EM shielding means comprising:
  - [[-]] electrically conductive shielding means mountable adjacent the electronic component at least partially to surround the electronic component; and
  - [[-]] resiliently biased electrically conductive connection means in electrical communication with the shielding means and operable electrically to connect the shielding means to a predetermined voltage by bearing down upon an electrically conductive contact of the circuit board forming a solder-less detachable electrical connection between the resiliently biased electrically conductive connection member and the electrically conductive contact.
- 20. (Cancelled).
- 21. (Currently Amended) A method for providing electromagnetic (EM) shielding for an electronic component mounted on a circuit board, the circuit board comprising an electrically conductive contact for providing a connection to a predetermined voltage, the method comprising:
  - [[-]] providing an EM shielding assembly comprising an electrically conductive shielding portion and at least one resiliently biased electrically conductive connection member in electrical communication with the shielding portion; and
  - [[-]] mounting the shielding portion adjacent the electronic component such that:
    - [[-]] the shielding portion at least partially surrounds the component; and

[[-]] the connection member electrically connects the shielding portion to the predetermined voltage by bearing down upon the electrically conductive contact forming a solder-less detachable electrical connection between the resiliently biased electrically conductive connection member and the electrically conductive contact.

## 22. (New) An apparatus, comprising:

a substrate, wherein the substrate comprises at least one electrically conductive contact; an integrated circuit coupled to the substrate;

an electrically conductive shield mountable adjacent the integrated circuit;

a biasing element coupled to the electrically conductive shield;

a connection member, wherein the connection member is biased onto the electrically conductive contact by the biasing element and wherein the connection member forms a detachable electrical connection between the electrically conductive shield and the electrically conductive contact.

23. (New) The apparatus of claim 22, wherein the biasing element is a spring, and wherein the biasing element compresses as the connection member is biased onto the electrically conductive contact.